

*Application No.: 10/086,016*

AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph beginning on page 1, line 4, with the following rewritten paragraph:

--The present application is a continuation of U.S. Patent Application Serial No. 10/086,016, filed February 28, 2002, entitled METHOD OF MAKING A HYBRID SUBSTRATE HAVING A THIN SILICON CARBIDE MEMBRANE LAYER to Torvik, which claims priority from pending provisional patent application Serial No. 60/272,532 filed March 1, 2001, entitled LARGE AREA HYBRID SiC WAFERS, each of which is incorporated herein by this reference.